

LEADFRAME-TO-PLASTIC LOCK FOR IC PACKAGE

ABSTRACT

[030] Disclosed is a method of making a mold lock for bonding leadframe-to-plastic in an IC package. Steps include providing niches from opposing sides of the leadframe. The opposing niches are arranged such that an aperture and a mechanical key are formed within the leadframe material by the partial intersection of the niches. The key is encapsulated with mold compound to form a lock. An IC package mold lock in a leadframe is also disclosed, the lock having an aperture, a key, and mold compound encapsulating the key. Additionally, an IC package employing the leadframe-to-plastic lock is disclosed.